



Assembly Location Change Plus Mold Compound and Silver Epoxy Change for Platform Flash VOG20 Packages

XCN16001 (v1.0.1) June 20, 2016

Product Change Notice

Overview

The purpose of this notification is to communicate two changes to the 1-Mbit, 2-Mbit, and 4-Mbit Platform Flash devices of the Xilinx In-System Programmable Configuration PROMs.

- Assembly and finish plant location change for all TSSOP20 (VOG20) packages from the current Amkor Philippines to the ASE-SH, China location.
- Consolidation of both mold compound and silver epoxy material to ensure use of the same mold compound across all TSOP20 packages. The mold compound and silver epoxy for VOG20 packages will be changed to the same as the mold compound already in volume production for the new assembly house.

There is no change to the form, fit, or function of these devices.

Description

The TSOP20 assembly and finish plant is being moved from the current Amkor Philippines to the Advanced Semiconductor Engineering, Shanghai Inc. ASE-SH, China location. The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test.

As a part of this transition, the molding compound & silver epoxy used for the Platform Flash VOG20 Pb-free packages is also being changed from Sumitomo G700K to Hitachi CEL9240HF Epoxy molding compound & Ablestick 8290 to Hitachi Hitachi EN-4900GC silver epoxy. Both mold compound & silver epoxy material are used in the standard (Pb-free) VOG20 Platform Flash products which have been shipping in volume production for several years. These consolidations are designed in ASE-SH to make Platform Flash manufacturing more efficient and timely, enabling smoother supply to Xilinx customers. This is not a process or technology change and has no impact to form, fit, or function of the products.

Products Affected

This change affects (XC) grade device including all versions under specification control documentation (SCD) reference. Please reference the Traceability section for further information on identifying these products.

This notification applies only to the following Xilinx commercial part numbers (see [Table 1](#)).

Table 1: Affected Devices for the Platform Flash VOG20 package

Xilinx part number	Xilinx part number	Xilinx part number	Xilinx part number
XCF01SVOG20C	XCF02SVOG20C	XCF04SVOG20C	XCF04SVOG20C4294
XCF01SVOG20C0100	XCF02SVOG20C0100	XCF04SVOG20C0100	

Key Dates and Ordering Information

For more information, see the Assembly Location Change, Plus Mold Compound and Silver Epoxy Changes, for Platform Flash PROMs in VOG20 Packages Qualification Report ([RPT222](#)).

Traceability

Country of origin will be changed from PHL to CHINA under package bottom by molding ejector pin (refer to [Figure 2](#)), and pin# 1 indicator change from molding ejector to laser mark (refer to [Figure 1](#)) on package in new assembly ASE-SH. The Top marking and Country of Origin detail for method of Identification is in [Table 2](#).



Figure 1: Top Mark Detail



Figure 2: Country of Origin under bottom of package Mark Detail

Table 2: Top Marking and Country of Origin Code Detail

Current Marking	New Marking
7B: Assembly code	GO: New assembly code
PHL: Country of Origin	CHINA: New Country of Origin

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
02/22/2016	1.0	Initial Release
06/20/2016	1.0.1	Updated link to RPT222

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